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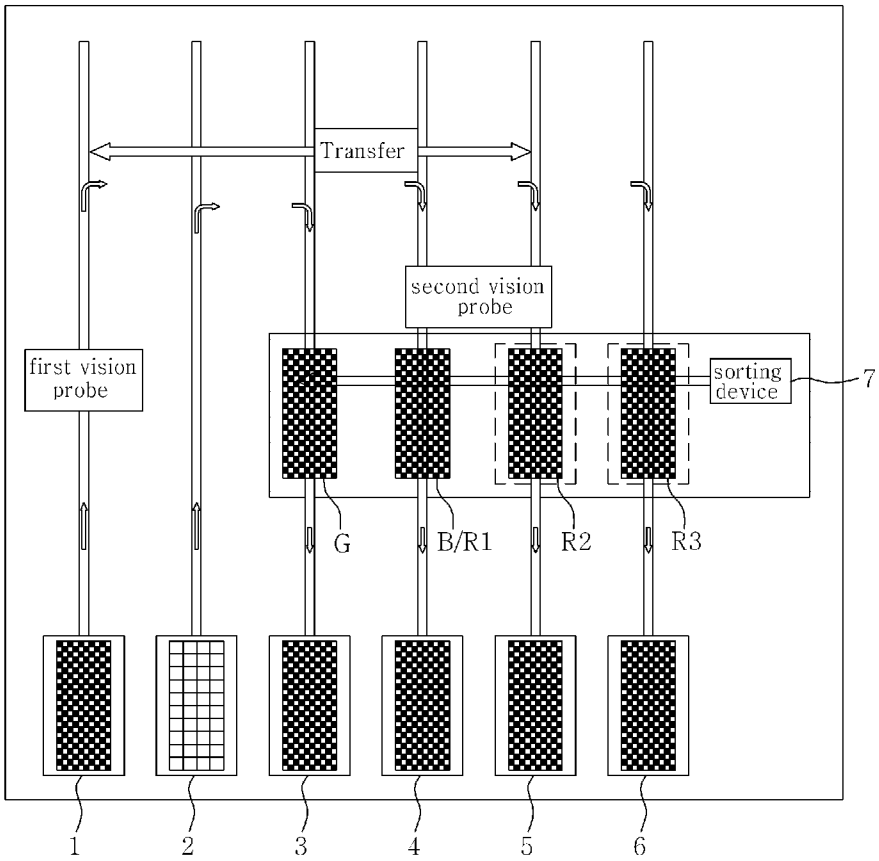
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(54) Title: SEMICONDUCTOR PACKAGE SORTING METHOD



(57) Abstract: Disclosed is a semiconductor package sorting method for improving sorting speed and yield of semiconductor packages. The method comprises performing a vision inspection on a tray, transferring the tray to a buffer unit, shifting defective products to a defective product tray, performing a vision inspection on a tray, transferring the tray to an unloading unit, determining whether defective products are found among semiconductor packages, if it is determined that the unloading tray receives defective products, shifting the defective products to the defective product tray and shifting normal products to fill the unloading tray, if a vision inspection for a last tray of a lot is completed, shifting the defective products to the defective product tray, discharging the defective product tray into a defective product storage unit, and if the re-inspection is determined, performing a defective product re-inspection simultaneously with arrangement of the normal products.

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